What Is Claimed Is:

1. A junction method of a spacer in a field emission display, comprising the steps of:

forming a fluorescent material on an anode substrate;

coating emulsion which is a planarization layer on the fluorescent material;

forming a frit at a predetermined position on the emulsion;

depositing a metal-back thin film on the frit; and

aligning and bonding the spacer on the anode substrate.

2. The method according to claim 1, wherein the fluorescent material is patterned on the substrate and a black matrix is formed in the process for forming the fluorescent material.

3. The method according to claim 2, wherein the frit is printed on the black matrix and a binder included in the frit is removed according to a heat process in the process for forming the fluorescent material.

4. The method according to claim 1, wherein the metal-back thin film is planarized, the emulsion is removed, and a preliminary sintering of the frit is performed at the same time, by executing a heat process after depositing the metal-back thin film.

5. The method according to claim 1, wherein, in the step for aligning and bonding the spacer, the spacer is aligned on the frit area and bonded according to a heat process.

6. A junction method of a spacer in a field emission display, comprising the steps of:

forming a fluorescent material on an anode substrate;

forming a frit at a predetermined position on the fluorescent material;

coating emulsion which is a planarization layer on the fluorescent material;

depositing a metal-back thin film on the emulsion; and

aligning and bonding the spacer on the anode substrate.

7. The method according to claim 6, wherein, in the process for forming the fluorescent material, the fluorescent material is patterned on the substrate, and a black matrix is formed.

8. The method according to claim 7, wherein, in the process for forming the fluorescent material, the frit is printed on the black matrix, and a binder included in the frit is removed according to a heat process.

9. The method according to claim 6, wherein the metal-back thin film is planarized, the emulsion is removed, and a preliminary sintering of the frit is performed at the same time, by executing a heat process after depositing the metal-back thin film.

10. The method according to claim 6, wherein, in the step for aligning and bonding the spacer, the spacer is aligned on the frit area, and bonded thereto according to a heat process.